

Description

The ICS307-01 and ICS307-02 are versatile serially programmable clock sources which take up very little board space.

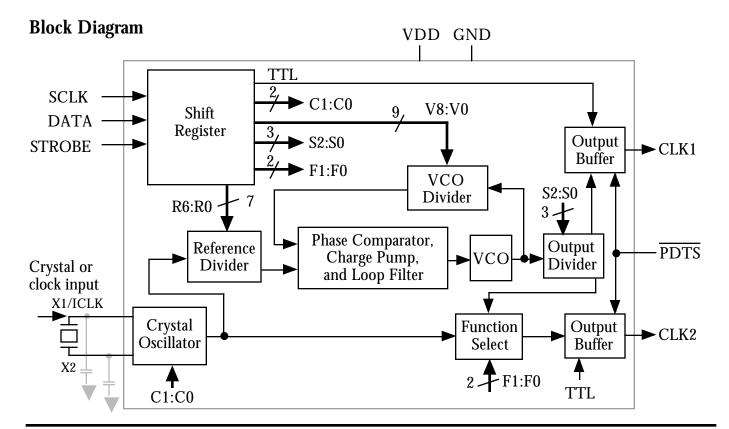
They can generate any frequency from 6 to 200 MHz, and have a second configurable output. The outputs can be reprogrammed on the fly, and will lock to a new frequency in 10 ms or less. Smooth transitions (in which the clock duty cycle remains roughly 50%) are guaranteed if the output divider is not changed.

The devices include a PDTS pin which tri-states the output clocks and powers down the entire chip.

The ICS307-02 features a default clock output at start-up and is recommended for all new designs.

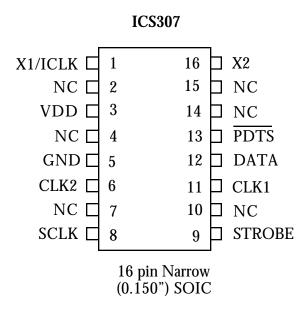
Features

- Packaged as 16 pin narrow SOIC
- Highly accurate frequency generation
- Serially programmable: user determines the output frequency via a 3 wire interface.
- Eliminates need for custom quartz
- Input crystal frequency of 5 27 MHz
- Output clock frequencies up to 200 MHz
- Power Down Tri-State mode
- Very low jitter
- Operating voltages of 3.0 to 5.5 V
- 25 mA drive capability at TTL levels
- Industrial temperature available





Pin Assignment



Pin Description

Number	Name	Туре	Description
1	X1/ICLK	XI	Crystal connection (REF frequency). Connect to a parallel resonant crystal, or an input clock .
2	NC	-	No Connect.
3	VDD	P	Connect to +3.3V or +5V.
4	NC	-	No Connect.
5	GND	P	Connect to ground.
6	CLK2	О	Output clock 2, determined by F0-F1. Can be reference, ref/2, CLK1/2 or off.
7	NC	-	No Connect.
8	SCLK	I	Serial clock. See timing diagram.
9	STROBE	I	Strobe to load data. See timing diagram.
10	NC	-	No Connect.
11	CLK1	0	Output clock 1, determined by R0-R6, V0-V8, S0-S2 and input frequency.
12	DATA	I	Data Input. Serial input for three words which set the output clock(s).
13	PDTS	I	Powers down entire chip, tri-states CLK1 and CLK2 outputs, when low. Internal pull-up.
14	NC	-	No Connect.
15	NC	-	No Connect.
16	X2	XO	Input crystal connection. Connect to a crystal, or leave unconnected for clock input.

Type: XI, XO=crystal connections, I = Input, O = output, P = power supply connection



Determining the Output Frequency

On power-up the ICS307-01 on-chip registers can have random values, so almost any frequency may be output from the part. CLK1 will always have some clock signal present, but CLK2 could possibly be OFF (low).

The ICS307-02 on-chip registers are initially configured to provide a x1 output clock on both the CLK1 and CLK2 outputs. The output frequency will be the same as the input clock or crystal. This is useful if the ICS307 will provide the initial system clock at power-up. Since this feature is an advantage in most systems, the ICS307-02 is recommended for new designs.

With programming, the user has full control in changing the desired output frequency to any value over the range shown in Table 1 on page 4. The output of the ICS307 can be determined by the following simple equation:

CLK1 frequency = Input frequency • 2 •
$$\frac{\text{(VDW+8)}}{\text{(RDW+2)(OD)}}$$

Where VCO Divider Word (VDW) = 4 to 511 (0, 1, 2, 3) are not permitted)

Reference Divider Word (RDW) = 1 to 127 (0 is not permitted)

Output Divider = values on page 4

Also, the following operating ranges should be observed:

55 MHz < Input frequency • 2 •
$$\frac{\text{(VDW+8)}}{\text{(RDW+2)}}$$
 < 400 MHz

Commercial temperature range. Industrial temperature limits are 60 MHz to 360 MHz.

$$200 \text{ kHz} < \frac{Input Frequency}{(RDW+2)}$$

To determine the best combination of VCO, reference, and output dividers, contact ICS application engineering. You may also fax this page to ICS at $408\ 295\ 9818$ (fax). Be sure to indicate the following:

Your Name _____ Company Name ____ Telephone _____ Or fax number ____ Desired input crystal ____ or clock ____ (in MHz) Desired output frequency ____ or 45-55% required ____



Setting the Device Characteristics

The tables below show the settings which can be configured, in addition to the VCO and Reference dividers.

Table 1. Output Divide and Maximum Output Frequency

S2	S1	S0	CLK1 Output Divide	Maximum Frequency 5 V or 3.3 V	Max. Freq. Industrial Version
0	0	0	10	40	36
0	0	1	2	200	180
0	1	0	8	50	45
0	1	1	4	100	90
1	0	0	5	80	72
1	0	1	7	55	50
1	1	0	3	135	120
1	1	1	6	67	60

Table 2. CLK2 Output

F1	F0	CLK2
0	0	REF
0	1	REF/2
1	0	OFF (Low)
1	1	CLK1/2

0 = Connect directy to ground1 = Connect directly to VDD

Table 3. Output Duty Cycle Configuration

TTL	Duty cycle measured at	Recommended VDD
0	1.4V	5 V
1	VDD/2	3.3 V

Note: The TTL bit optimizes the duty cycle at different VDD. When VDD is 5 V, set to 0 for a near-50% duty cycle with TTL levels. When VDD is 3.3 V, set this bit to a 1, so the 50% duty cycle is achieved at VDD/2.

Table 4. Crystal Load Capacitance

C1	C0	VDD = 5 V	VDD = 3.3 V
0	0	22.3 - 0.083 f	22.1 - 0.094 f
0	1	23.1 - 0.093 f	22.9 - 0.108 f
1	0	23.7 - 0.106 f	23.5 - 0.120 f
1	1	24.4 - 0.120 f	24.2 - 0.135 f

Note: f is the crystal frequency, between 10 and 27 MHz. Effective load capacitance will be higher for crystal frequencies lower than 10 MHz. If a clock input is used, set C1 = 0 and C0 = 0.



Configuring the ICS307

The ICS307 can be programmed to set the output functions and frequencies. The three data bytes are written to the DATA pin, in this order:

C1 C0 TTL F1 F	0 S2 S1 S0	V8 V7 V6 V	5 V4 V3 V2 V1	VO R6	R5 R4 R3	R2 R1	R0
MSB	LSB	MSB	LSB	MSB			LSB

C1 is loaded into the port first and R0 last.

R6:R0	Reference Divider Word (RDW)
V8:V0	VCO Divider Word (VDW)
S2:S0	Output Divider Select (OD)
F1:F0	Function of CLK2 Output
TTI	Duty Cycle Setting

C1:C0 Duty Cycle Setting
C1:C0 Internal Load Capacitance for Crystal

Power up default values for ICS 307-02

0	0	1	0	0	0	1	1	1	0	0	0	0	0	1	0	0]	0	0	0	0	0	1	1	0
U	U	1	U	U	U	1	1		U	U	0	U	U	1	U	U	ı		U	0	U	U	1	I	U

The input frequency will come from both outputs.

Programming Example

To generate 66.66 MHz from a 14.31818 MHz input, the RDW should be 59, the VDW should be 276, and the Output Divide is 2. Selecting the minimum internal load capacitance, CMOS duty cycle, and CLK2 to be OFF means that the following three bytes are sent to the ICS307:

00110001	10001010	00111011
Byte 1	Byte 2	Byte 3

As shown in Figure 2, after these 24 bits are clocked into the ICS307, taking STROBE high will send this data to the internal latch, and the CLK output will lock within 10 ms.

NOTE: If STROBE is in the high state and SCLK is pulsed, DATA is clocked directly to the internal latch and the output conditions will change accordingly. Although this will not damage the ICS307, it is recommended that STROBE be kept low while DATA is being clocked into the ICS307 in order to avoid unintended changes on the output clocks.



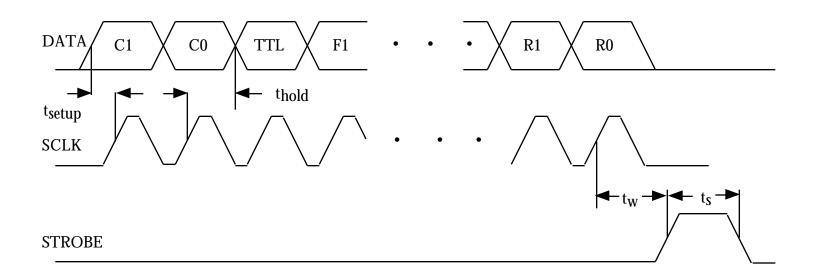


Figure 2. Timing Diagram for Programming the ICS307

AC Parameters for Writing to the ICS307

Parameter	Condition	Min	Max	Units
tsetup	Setup time.	10		ns
tHOLD	Hold time after SCLK.	10		ns
$t_{\rm w}$	Data wait time.	10		ns
ts	Strobe pulse width	40		ns

External Components / Crystal Selection

The ICS307 require a $0.01\mu F$ decoupling capacitor to be connected between VDD and GND. It must be connected close to the ICS307 to minimize lead inductance. A 33 terminating resistor can be used in series with the CLK1 and CLK2 outputs. A parallel resonant, fundamental mode crystal with a load (correlation) capacitance of C should be used, where C is the value calculated from Table 4. For crystals with a specified load capacitance greater than C, additional crystal capacitors may be connected from each of the pins X1 and X2 to Ground as shown in the Block Diagram on page 1. The value (in pF) of these crystal caps should be = $(C_L-C)^*2$, where C_L is the crystal load capacitance in pF. These external capacitors are only required for applications where the exact frequency is critical. For a clock input, connect to X1 and leave X2 unconnected (no capacitors on either pin).



Electrical Specifications

Parameter	Conditions	Minimum	Typical	Maximum	Units
ABSOLUTE MAXIMUM RATINGS (Note 1)					
Supply Voltage, VDD	Referenced to GND			7	V
Inputs	Referenced to GND	-0.5		VDD+0.5	V
Clock Output	Referenced to GND	-0.5		VDD+0.5	V
Ambient Operating Temperature		0		70	°C
Ambient Operating Temperature, Industrial	I version	-40		85	°C
Soldering Temperature	Max of 10 seconds			260	°C
Storage temperature		-65		150	°C
DC CHARACTERISTICS (VDD = 5.0 V unless other	nerwise noted)				
Operating Voltage, VDD		3		5.5	V
Input High Voltage, VIH, X1/ICLK only	ICLK (Pin 1)	(VDD/2)+1	VDD/2		V
Input Low Voltage, VIL, X1/ICLK only	ICLK (Pin 1)		VDD/2	(VDD/2)-1	V
Input High Voltage, VIH		2			V
Input Low Voltage, VIL	PDTS, ICS307-01 only			0.4	V
	All other inputs,-01 & -02			0.8	
Output High Voltage, VOH, CMOS level	IOH=-4 mA	VDD-0.4			V
Output High Voltage, VOH	IOH=-25 mA	2.4			V
Output Low Voltage, VOL	IOL=25 mA			0.4	V
IDD Operating Supply Current, 20 MHz crystal	No Load, 100 MHz out		26		mA
	100MHz out,VDD=3.3V		13		mA
Short Circuit Current	CLK1 and CLK2 outputs		±70		mA
On-Chip Pull-up Resistor	Pin 13		270		k
Input Capacitance			4		pF
AC CHARACTERISTICS					
Input Frequency, crystal input (must be fundamental)		5		27	MHz
Input Frequency, clock input		2		50	MHz
Output Frequency (See Table 1)	VDD = 3.0 to 5.5V	6		200	MHz
Output Frequency (see Table 1), I version	VDD = 3.0 to 5.5V	6		180	MHz
Output Clock Rise Time	0.8 to 2.0V		1		ns
Output Clock Fall Time	2.0 to 0.8V		1		ns
Output Clock Duty Cycle, even output divides	At duty cycle level	45	49 to 51	55	%
Output Clock Duty Cycle, odd output divides	At duty cycle level	40		60	%
Power-up time, STROBE goes high until CLK out			3	10	ms
Absolute Maximum Clock Period Jitter	Deviation from mean		±120		ps
One Sigma Clock Period Jitter			50		ps

Notes:

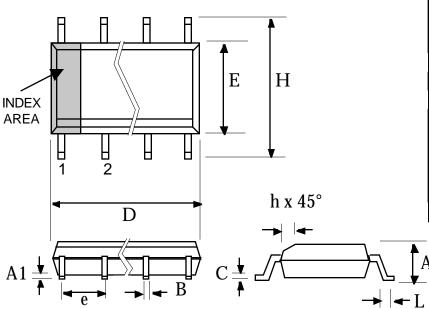
^{1.} Stresses beyond those listed under Absolute Maximum Ratings could cause permanent damage to the device. Prolonged exposure to levels above the operating limits but below the Absolute Maximums may affect device reliability.

^{2.} Typical values are at 25°C.



Package Outline and Package Dimensions

(For current dimensional specifications, see JEDEC Publication No. 95.)



16 pin SOIC narrow

	Incl	nes	Millin	neters
Symbol	Min	Max	Min	Max
A	0.0532	0.0688	1.35	1.75
A1	0.0040	0.0098	0.10	0.24
В	0.0130	0.0200	0.33	0.51
С	0.0075	0.0098	0.19	0.24
D	0.3859	0.3937	9.80	10.00
E	0.1497	0.1574	3.80	4.00
e	.050 BS	C	1.27 B	SC
Н	0.2284	0.2440	5.80	6.20
h	0.0099	0.0195	0.25	0.50
Ī.	0.0160	0.0500	0.41	1 27

Ordering Information

Part/Order Number	Marking	Package	Temperature
ICS307M-01	ICS307M-01	16 pin SOIC	0 to 70 °C
ICS307M-01T	ICS307M-01	16 pin SOIC on tape and reel	0 to 70 °C
ICS307M-01I	ICS307M-01I	16 pin SOIC	-40 to 85°C
ICS307M-01IT	ICS307M-01I	16 pin SOIC on tape and reel	-40 to 85°C
ICS307M-02	ICS307M-02	16 pin SOIC	0 to 70 °C
ICS307M-02T	ICS307M-02	16 pin SOIC on tape and reel	0 to 70 °C
ICS307M-02I	ICS307M-02I	16 pin SOIC	-40 to 85°C
ICS307M-02IT	ICS307M-02I	16 pin SOIC on tape and reel	-40 to 85°C

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